

PAGE 66 OF APPLICATION

The patterned face-electrode layer is typically formed by depositing a blanket layer of the desired face-electrode material and selectively removing undesired parts of the face-electrode material using a suitable mask to prevent the face-electrode material from being removed at the intended locations for the face electrodes. Alternatively, the patterned face-electrode layer can be selectively deposited using, for example, a shadow mask to prevent the face-electrode material from accumulating at undesired locations. When the patterned face-electrode material overlies one of conformal coatings 138 and 140 and/or one of rough layers 134 and 136, use of this alternative avoids possible contamination of rough faces 54 and 56 with material used in forming the face electrodes.

Other modifications can be made to the foregoing spacer fabrication process. For example, the support structure can be eliminated. End electrodes 50 and 52 can be formed in different ways than described above. Instead of cutting the precursor substrate into core substrates 132 and then using a shadow mask to prevent the end-electrode material from being deposited on the side edges of substrates 132, the precursor substrate and overlying material can be cut into strips that each contain a row (or column) of substrates 132 arranged side edge to side edge. After the end-electrode material is deposited, the strips are then cut into segments that each contain one substrate 132. In some cases, the formation of end electrodes 50 and 52 and/or the formation of face electrodes such as face electrodes 48 can be eliminated. The spacer fabrication process is then simplified accordingly.

All of the steps involved in the formation of the patterned face-electrode material, end electrodes 50 and 52, rough layers 134 and 136, and conformal